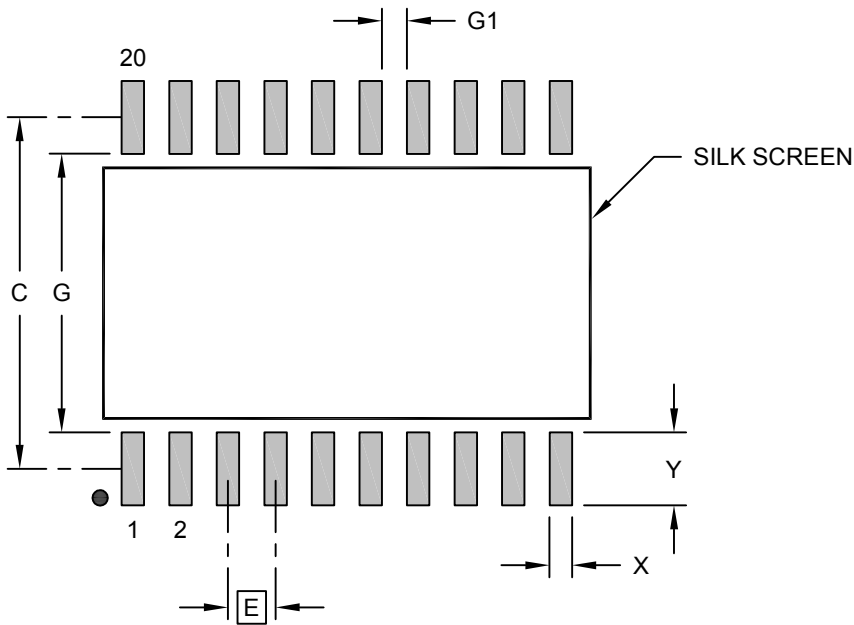


20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

| | | Units | MILLIMETERS | | |
|----------------------------|----|-------|-------------|------|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Contact Pitch | E | | 1.27 BSC | | |
| Contact Pad Spacing | C | | | 9.40 | |
| Contact Pad Width (X20) | X | | | | 0.60 |
| Contact Pad Length (X20) | Y | | | | 1.95 |
| Contact Pad to Contact Pad | G | 0.67 | | | |
| Contact Pad to Contact Pad | G1 | 7.45 | | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process